



Thermal Data

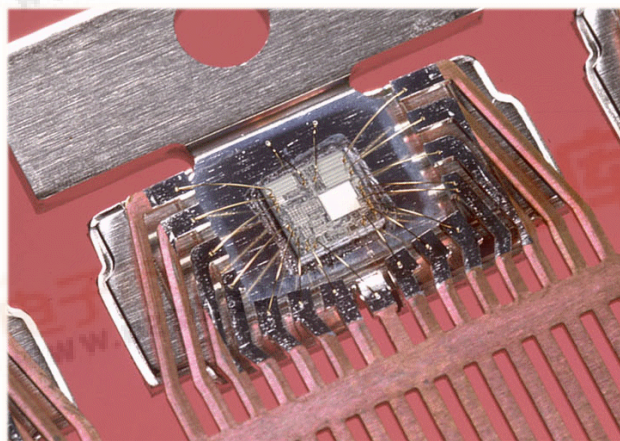
MULTIWATT Family 8,11,15 leads (JEDEC MO-048)



PACKAGE MATERIAL LIST

item #	material	thickness	thermal conductivity
leadframe	copper	0.5 mm	3.9 W/cm°C
slug	high thermal conductivity Cu	1.5 mm	3.9 W/cm°C
die attach	soft solder (tin / lead)	15-50 μm	0.2 W/cm°C
molding compound	epoxy resin	3 mm	0.0063W/cm°C

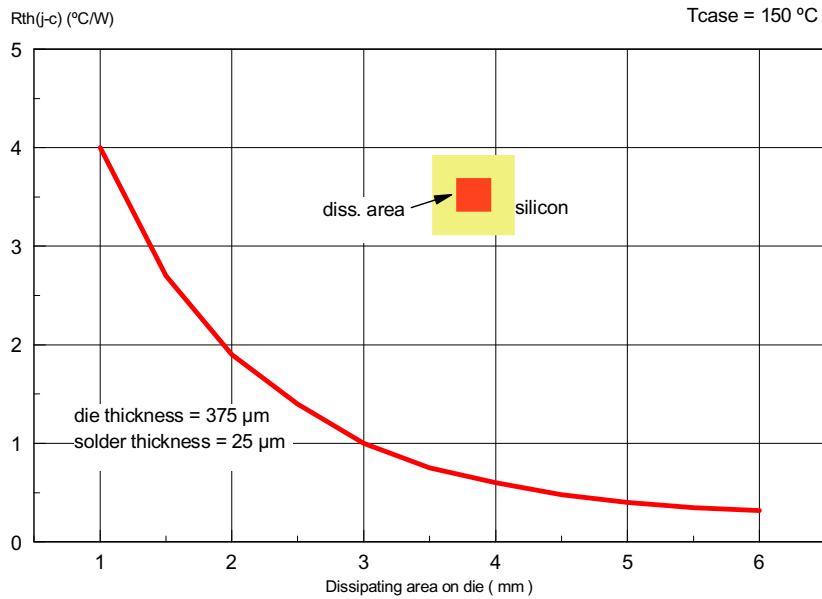
Typical assembly configuration before molding :



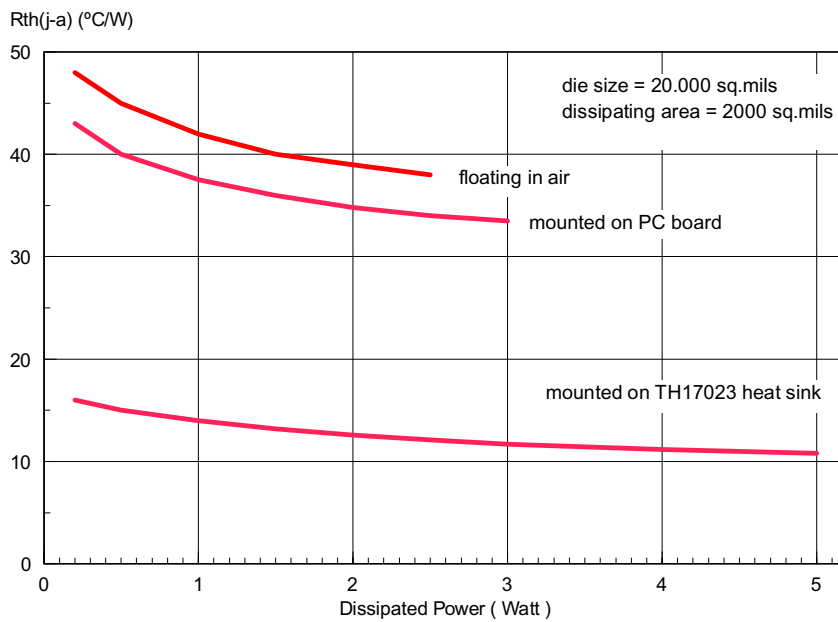
Charts enclosed :

- 1) $R_{th(j-c)}$ vs. die size and dissipating area
- 2) $R_{th(j-a)}$ vs on board heat sink area
- 3) $Z_{th(j-a)}$ vs time width and die size

1)



2)



3)

